

# N-Channel 60 V (D-S) MOSFET

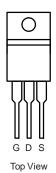
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0035			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0090			
I <sub>D</sub> (A)	210			
Configuration	Single			

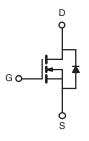
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		$V_{DS}$	60			
Gate-Source Voltage		$V_{GS}$	± 20	V		
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	210			
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	120 <sup>a</sup>			
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	120 <sup>a</sup>	Α		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	480	1		
Single Pulse Avalanche Current	L = 0.1 mH	l <sub>AS</sub>	75			
Single Pulse Avalanche Energy	L=0.1 MH	E <sub>AS</sub>	281	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	375	W		
	T <sub>C</sub> = 125 °C	r <sub>D</sub>	125	VV		
Operating Junction and Storage Temperature Range	Э	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	40	°C/W	
Junction-to-Case (Drain)		$R_{thJC}$	0.4	C/ VV	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							,
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.0	-	3.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1.0	μА
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	350	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.0035	-	- Ω
Drain Sauras On State Besistance	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	0.0060	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	0.0080	-	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A	-	0.0090	-	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	109	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	8600	-	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	1000	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	750	-	
Total Gate Charge <sup>c</sup>	Qg			-	180	-	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $V_{DS} = 30 \text{ V}, I_D = 110 \text{ A}$		24.7	-	nC
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$				50.4	-	
Gate Resistance	$R_{g}$	f = 1 MHz		0.5	1.1	1.6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				19	29	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.27 \Omega$ $I_{D} \cong 110 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_{g} = 2.5 \Omega$		-	23	35	ns ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	83	125	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	35	53	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	Α
Forward Voltage	$V_{SD}$	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0		-	0.9	1.5	V

#### Notes

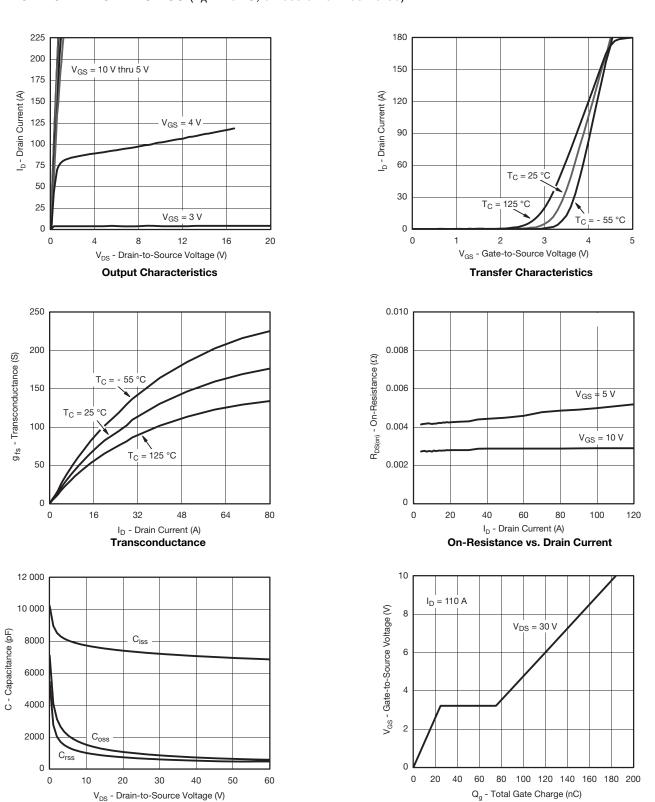
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

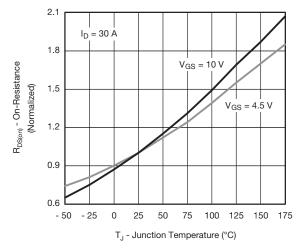
Capacitance

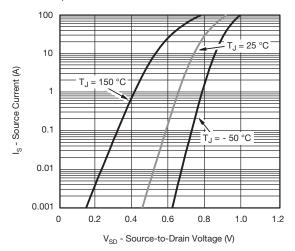


**Gate Charge** 

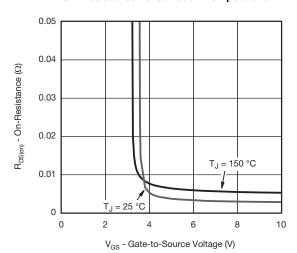


## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)

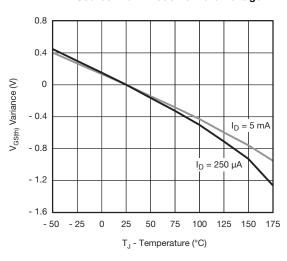




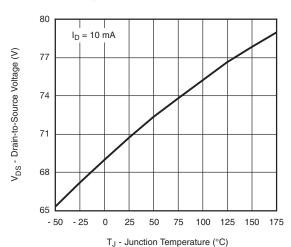
#### On-Resistance vs. Junction Temperature



Source Drain Diode Forward Voltage



#### On-Resistance vs. Gate-to-Source Voltage

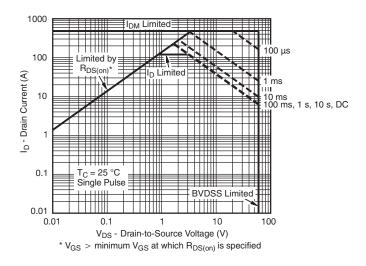


#### Threshold Voltage

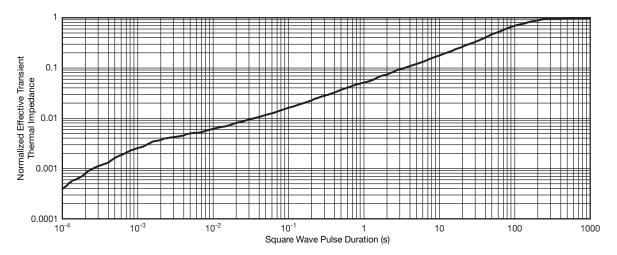
**Drain Source Breakdown vs. Junction Temperature** 



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



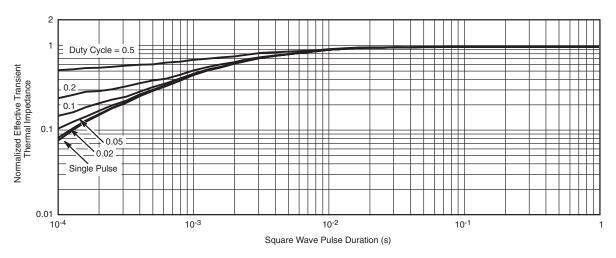
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



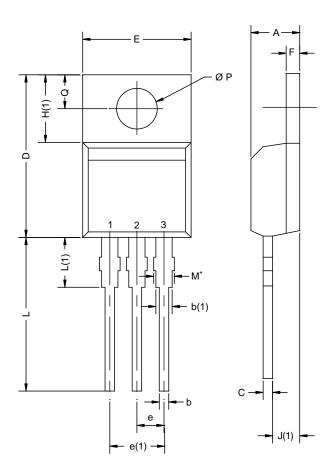
#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



# **TO-220AB**



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

#### Notes

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 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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